



Semiconductor Materials Information

Dielectric Precursors – STI, Gapfill, Patterning and Interlayer Dielectrics

For Semiconductor Device Manufacturing

Techcet Group

a Techcet CA, LLC Company

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REPORT DESCRIPTION: *Techcet's Critical Materials Report on Dielectric Precursors provides detailed information on the markets dynamics, supply chain and technical trends associated with front end of line and back end of line dielectrics, including STI, Gapfill, Low temperature and Low K dielectrics. How and where these are used in addition to the descriptions of the various dielectrics and precursors are provided, in addition to market statistics and supplier profiles. Materials market forecasts as well as supplier market ranking are also included.*

* www.techcet.com

Lshonroy@techcet.com

Ph: +1-480-382-8336

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